

# HEXFRED® Ultrafast Soft Recovery Diode, 210 A



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	210 A			
$V_{R}$	600 V			
I <sub>F(DC)</sub> at T <sub>C</sub>	120 A at 100 °C			
Package	TO-244			
Circuit configuration	Two diodes common cathode			

#### **FEATURES**

- Very low Q<sub>rr</sub> and t<sub>rr</sub>
- UL approved file E222165



- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **BENEFITS**

- · Reduced RFI and EMI
- · Reduced snubbing

#### **DESCRIPTION / APPLICATIONS**

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl<sub>F</sub>/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	$V_R$		600	V	
Continuous forward current	1	T <sub>C</sub> = 25 °C	235		
Continuous forward current	l <sub>F</sub>	T <sub>C</sub> = 100 °C	120	Α	
Single pulse forward current	I <sub>FSM</sub>	Limited by junction temperature	600		
Non-repetitive avalanche energy	E <sub>AS</sub>	$L = 100 \mu H$ , duty cycle limited by maximum $T_J$	2.2	mJ	
lovimum nower dissinction		T <sub>C</sub> = 25 °C	463	W	
Maximum power dissipation	P <sub>D</sub>	T <sub>C</sub> = 100 °C	185	VV	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C	

<b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	$V_{BR}$	I <sub>R</sub> = 100 μA		600	-	-	
		I <sub>F</sub> = 105 A		-	1.38	1.9	V
Maximum forward voltage	$V_{FM}$	I <sub>F</sub> = 210 A	See fig. 1	-	1.6	2.25	
		I <sub>F</sub> = 105 A, T <sub>J</sub> = 125 °C		-	1.3	1.56	
Maximum reverse leakage current	I <sub>RM</sub>	T <sub>J</sub> = 125 °C, V <sub>R</sub> = 480 V	See fig. 2	-	1.8	6.0	mA
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V	See fig. 3	-	200	300	pF
Series inductance	L <sub>S</sub>	From top of terminal hole to mounting plane - 6.0 -		nH			



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST C	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	35	-		
Reverse recovery time (fig. 5)	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	90	140	ns	
		T <sub>J</sub> = 125 °C		-	160	240		
Dook recovery overset (fig. 6)	I <sub>RRM</sub>	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 105 A dI <sub>F</sub> /dt = 200 A/μs	-	10	18	۸
Peak recovery current (fig. 6)			T <sub>J</sub> = 125 °C		=	15	30	А
Reverse recovery charge (fig. 7)	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	$V_{\rm R} = 200 \text{ V}$	-	450	1300	nC	
neverse recovery charge (fig. 7)		T <sub>J</sub> = 125 °C	Q <sub>rr</sub>	-	1200	3600	iiC	
Dook rate of recovery current (fig. 9)	Peak rate of recovery current (fig. 8) dI <sub>(rec)M</sub> /dt	dl <sub>(rec)M</sub> /dt	T <sub>J</sub> = 25 °C		=	310	-	A/µs
reak rate of recovery current (fig. 6)			T <sub>J</sub> = 125 °C		-	240	=	AvμS

PARAMETER  Maximum junction and storage temperature range		SYMBOL T <sub>J</sub> , T <sub>Stg</sub>	MIN.	TYP.	<b>MAX.</b> 150	°C	
			-55				
The per leg		D	-	-	0.27		
Thermal resistance, junction to case	per module	$R_{thJC}$	-	-	0.135	°C/W K/W	
Typical thermal resistance, case to heatsink		R <sub>thCS</sub>	-	0.10	-	1	
Weight			-	68	-	g	
			-	2.4	-	oz.	
Mounting torque (1)			30 (3.4)	-	40 (4.6)		
Mounting torque center hole			12 (1.4)	-	18 (2.1)	lbf · in (N · m)	
Terminal torque			30 (3.4)	=	40 (4.6)		
Vertical pull			-	=	80	lbf ⋅ in	
2" lever pull			-	-	35	IDT · IN	

#### Note

<sup>(1)</sup> Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached

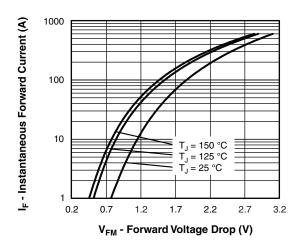


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

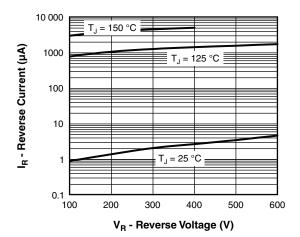


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

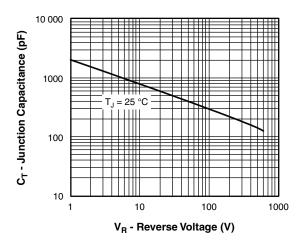


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

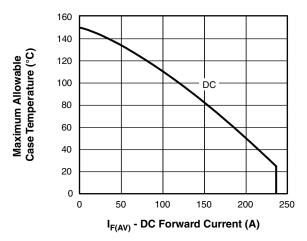


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leq)

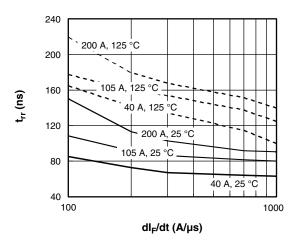


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

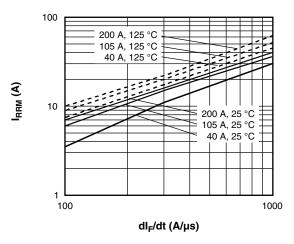


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

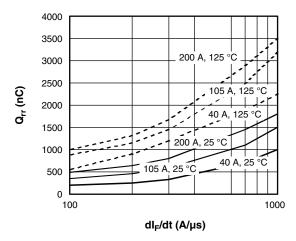


Fig. 7 - - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

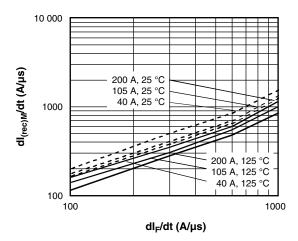


Fig. 8 - - Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)

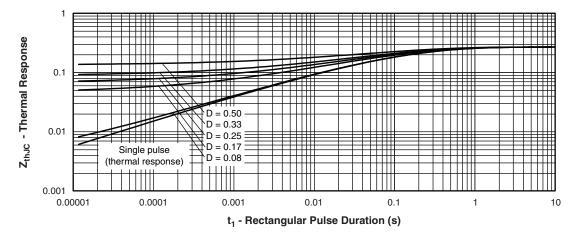


Fig. 9 - - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)

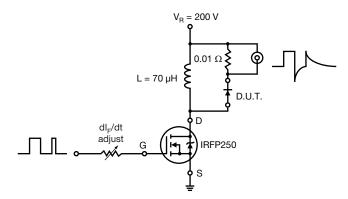
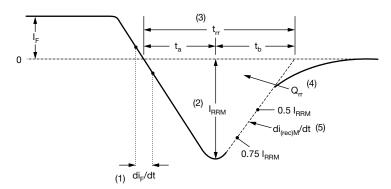


Fig. 10 - - Reverse Recovery Parameter Test Circuit



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $t_{rr}$  reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75 I<sub>RRM</sub> and 0.50 I<sub>RRM</sub> extrapolated to zero current.
- (4) Q<sub>rr</sub> area under curve defined by t<sub>rr</sub> and I<sub>RRM</sub>

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 11 - Reverse Recovery Waveform and Definitions



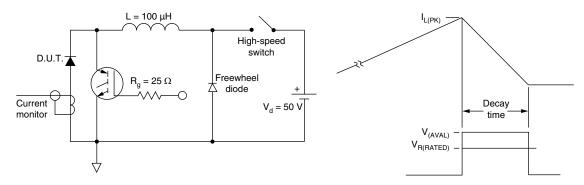
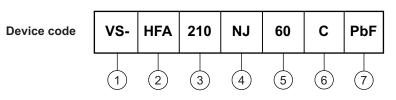


Fig. 12 - Avalanche Test Circuit and Waveforms

#### **ORDERING INFORMATION TABLE**



1 - Vishay Semiconductors product

2 - HEXFRED® family, electron irradiated

3 - Average current rating

**4** - NJ = TO-244

5 - Voltage rating (60 = 600 V)

6 - C = two diodes common cathode

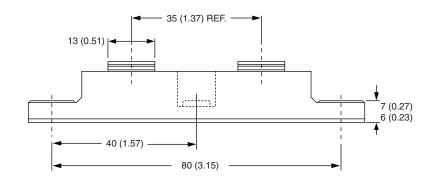
7 - Lead (Pb)-free

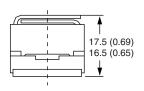
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95021			

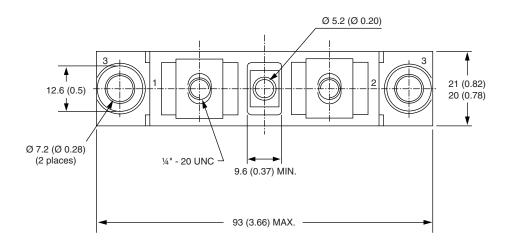


## **TO-244**

#### **DIMENSIONS** in millimeters (inches)









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